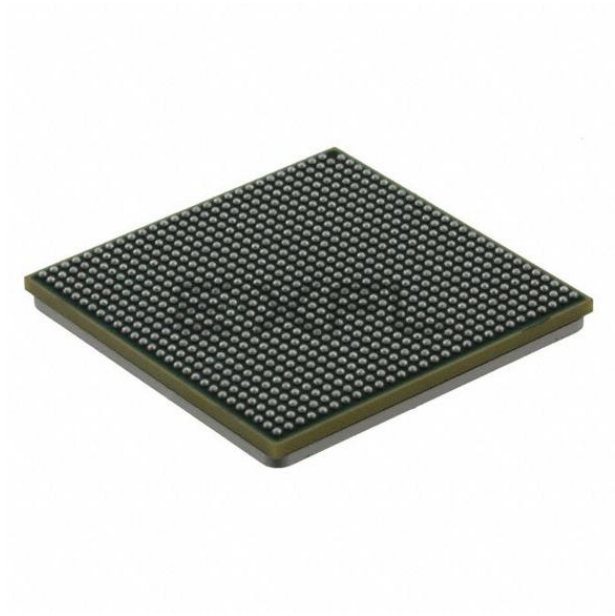

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	PowerPC e500
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	667MHz
Co-Processors/DSP	Signal Processing; SPE
RAM Controllers	DDR, DDR2, SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100/1000Mbps (2)
SATA	-
USB	-
Voltage - I/O	1.8V, 2.5V, 3.3V
Operating Temperature	-40°C ~ 105°C (TA)
Security Features	-
Package / Case	783-BBGA, FCBGA
Supplier Device Package	783-FCPBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc8544cvjalfa

  - General-purpose chip select machine (GPCM)
  - Three user programmable machines (UPMs)
- Parity support
- Default boot ROM chip select with configurable bus width (8, 16, or 32 bits)

- Two enhanced three-speed Ethernet controllers (eTSECs)
  - Three-speed support (10/100/1000 Mbps)
  - Two IEEE Std 802.3™, IEEE 802.3u, IEEE 802.3x, IEEE 802.3z, IEEE 802.3ac, and IEEE 802.3ab-compliant controllers
  - Support for various Ethernet physical interfaces:
    - 1000 Mbps full-duplex IEEE 802.3 GMII, IEEE 802.3z TBI, RTBI, SGMII, and RGMII.
    - 10/100 Mbps full- and half-duplex IEEE 802.3 MII, IEEE 802.3 RGMII, and RMII.
  - Flexible configuration for multiple PHY interface configurations.
  - TCP/IP acceleration and QoS features available
    - IP v4 and IP v6 header recognition on receive
    - IP v4 header checksum verification and generation
    - TCP and UDP checksum verification and generation
    - Per-packet configurable acceleration
    - Recognition of VLAN, stacked (queue in queue) VLAN, 802.2, PPPoE session, MPLS stacks, and ESP/AH IP-security headers
    - Supported in all FIFO modes
  - Quality of service support:
    - Transmission from up to eight physical queues
    - Reception to up to eight physical queues
  - Full- and half-duplex Ethernet support (1000 Mbps supports only full duplex):
    - IEEE 802.3 full-duplex flow control (automatic PAUSE frame generation or software-programmed PAUSE frame generation and recognition)
  - Programmable maximum frame length supports jumbo frames (up to 9.6 Kbytes) and IEEE Std 802.1™ virtual local area network (VLAN) tags and priority
  - VLAN insertion and deletion
    - Per-frame VLAN control word or default VLAN for each eTSEC
    - Extracted VLAN control word passed to software separately
  - Retransmission following a collision
  - CRC generation and verification of inbound/outbound frames
  - Programmable Ethernet preamble insertion and extraction of up to 7 bytes
  - MAC address recognition:
    - Exact match on primary and virtual 48-bit unicast addresses
    - VRRP and HSRP support for seamless router fail-over
    - Up to 16 exact-match MAC addresses supported

Figure 10 provides the AC test load for SGMII.

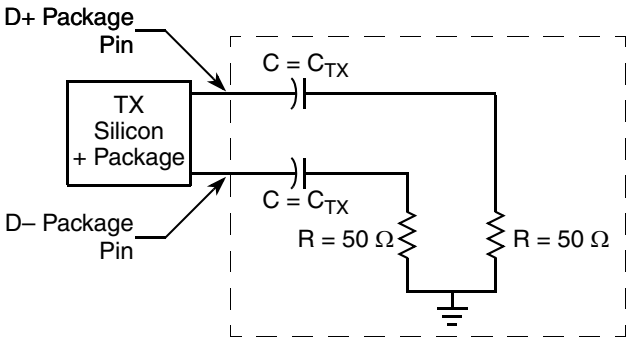


Figure 10. SGMII AC Test/Measurement Load

8.5 FIFO, GMII,MII, TBI, RGMII, RMII, and RTBI AC Timing Specifications

The AC timing specifications for FIFO, GMII, MII, TBI, RGMII, RMII, and RTBI are presented in this section.

8.5.1 FIFO AC Specifications

The basis for the AC specifications for the eTSEC FIFO modes is the double data rate RGMII and RTBI specifications, since they have similar performance and are described in a source-synchronous fashion like FIFO modes. However, the FIFO interface provides deliberate skew between the transmitted data and source clock in GMII fashion.

When the eTSEC is configured for FIFO modes, all clocks are supplied from external sources to the relevant eTSEC interface. That is, the transmit clock must be applied to the eTSEC*n* TSEC*n*_TX_CLK, while the receive clock must be applied to pin TSEC*n*_RX_CLK. The eTSEC internally uses the transmit clock to synchronously generate transmit data and outputs an echoed copy of the transmit clock back out onto the TSEC*n*_GTX_CLK pin (while transmit data appears on TSEC*n*_TXD[7:0], for example). It is intended that external receivers capture eTSEC transmit data using the clock on TSEC*n*_GTX_CLK as a source-synchronous timing reference. Typically, the clock edge that launched the data can be used, since the clock is delayed by the eTSEC to allow acceptable set-up margin at the receiver.

A summary of the FIFO AC specifications appears in Table 28 and Table 29.

Table 28. FIFO Mode Transmit AC Timing Specification

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Notes
TX_CLK, GTX_CLK clock period	t_{FIT}	—	8.0	—	ns	—
TX_CLK, GTX_CLK duty cycle	t_{FITH}	45	50	55	%	—
TX_CLK, GTX_CLK peak-to-peak jitter	t_{FITJ}	—	—	250	ps	—
Rise time TX_CLK (20%–80%)	t_{FITR}	—	—	0.75	ns	—

Table 28. FIFO Mode Transmit AC Timing Specification (continued)

(continued)At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Notes
Fall time TX_CLK (80%–20%)	t_{FITF}	—	—	0.75	ns	—
GTX_CLK to FIFO data TXD[7:0], TX_ER, TX_EN hold time	t_{FITDX}	0.5	—	3.0	ns	1

Note:

1. Data valid t_{FITDV} to GTX_CLK Min setup time is a function of clock period and max hold time. (Min setup = Cycle time – Max hold).

Table 29. FIFO Mode Receive AC Timing Specification

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Notes
RX_CLK clock period	t_{FIR}	—	8.0	—	ns	—
RX_CLK duty cycle	t_{FIRH}/t_{FIRH}	45	50	55	%	—
RX_CLK peak-to-peak jitter	t_{FIRJ}	—	—	250	ps	—
Rise time RX_CLK (20%–80%)	t_{FIRR}	—	—	0.75	ns	—
Fall time RX_CLK (80%–20%)	t_{FIRF}	—	—	0.75	ns	—
RXD[7:0], RX_DV, RX_ER setup time to RX_CLK	t_{FIRDV}	1.5	—	—	ns	—
RX_CLK to RXD[7:0], RX_DV, RX_ER hold time	t_{FIRDX}	0.5	—	—	ns	—

Timing diagrams for FIFO appear in Figure 11 and Figure 12.

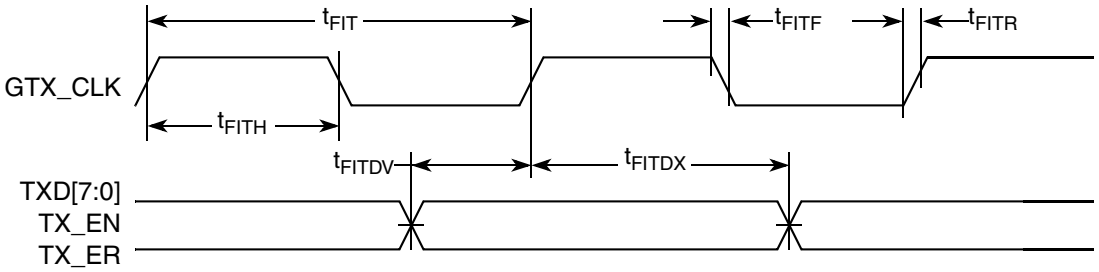


Figure 11. FIFO Transmit AC Timing Diagram

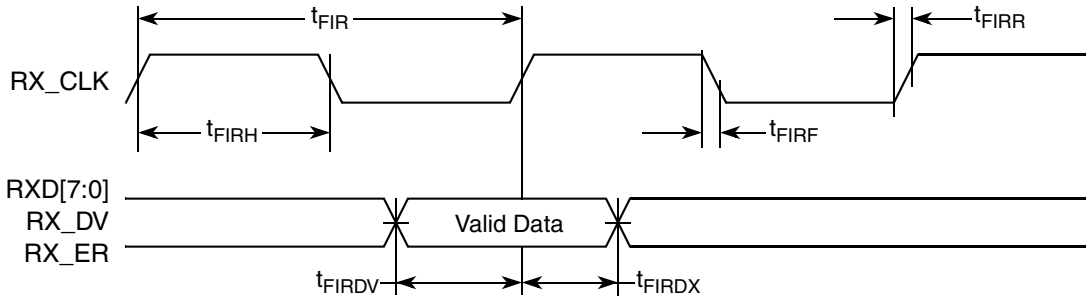


Figure 12. FIFO Receive AC Timing Diagram

8.6.1 MII Transmit AC Timing Specifications

Table 32 provides the MII transmit AC timing specifications.

Table 32. MII Transmit AC Timing Specifications

At recommended operating conditions with L/TV_{DD} of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
TX_CLK clock period 10 Mbps	t_{MTX}	—	400	—	ns	—
TX_CLK clock period 100 Mbps	t_{MTX}	—	40	—	ns	—
TX_CLK duty cycle	t_{MTXH}/t_{MTX}	35	—	65	%	—
TX_CLK to MII data TXD[3:0], TX_ER, TX_EN delay	t_{MTKHDX}	1	5	15	ns	—
TX_CLK data clock rise (20%–80%)	t_{MTXR}	1.0	—	4.0	ns	—
TX_CLK data clock fall (80%–20%)	t_{MTXF}	1.0	—	4.0	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{MTKHDX} symbolizes MII transmit timing (MT) for the time t_{MTX} clock reference (K) going high (H) until data outputs (D) are invalid (X). Note that, in general, the clock reference symbol representation is based on two to three letters representing the clock of a particular functional. For example, the subscript of t_{MTX} represents the MII(M) transmit (TX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

Figure 16 shows the MII transmit AC timing diagram.

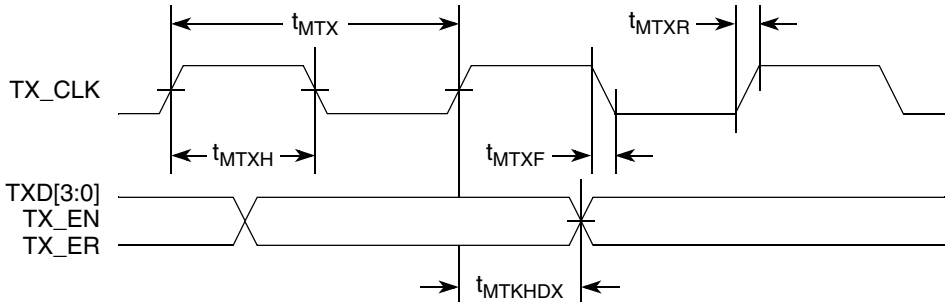


Figure 16. MII Transmit AC Timing Diagram

8.6.2 MII Receive AC Timing Specifications

Table 33 provides the MII receive AC timing specifications.

Table 33. MII Receive AC Timing Specifications

At recommended operating conditions with L/TVDD of 3.3 V ± 5%.or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
RX_CLK clock period 10 Mbps	t_{MRX}	—	400	—	ns	—
RX_CLK clock period 100 Mbps	t_{MRX}	—	40	—	ns	—
RX_CLK duty cycle	t_{MRXH}/t_{MRX}	35	—	65	%	—

Table 35. TBI Receive AC Timing Specifications (continued)

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
PMA_RX_CLK[0:1] duty cycle	t_{TRXH}/t_{TRX}	40	—	60	%	—
RCG[9:0] setup time to rising PMA_RX_CLK	t_{TRDVKH}	2.5	—	—	ns	—
PMA_RX_CLK to RCG[9:0] hold time	t_{TRDXKH}	1.5	—	—	ns	—
PMA_RX_CLK[0:1] clock rise time (20%-80%)	t_{TRXR}	0.7	—	2.4	ns	—
PMA_RX_CLK[0:1] clock fall time (80%-20%)	t_{TRXF}	0.7	—	2.4	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{TRDVKH} symbolizes TBI receive timing (TR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{TRX} clock reference (K) going to the high (H) state or setup time. Also, t_{TRDXKH} symbolizes TBI receive timing (TR) with respect to the time data input signals (D) went invalid (X) relative to the t_{TRX} clock reference (K) going to the high (H) state. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{TRX} represents the TBI (T) receive (RX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall). For symbols representing skews, the subscript is skew (SK) followed by the clock that is being skewed (TRX).

Figure 20 shows the TBI receive AC timing diagram.

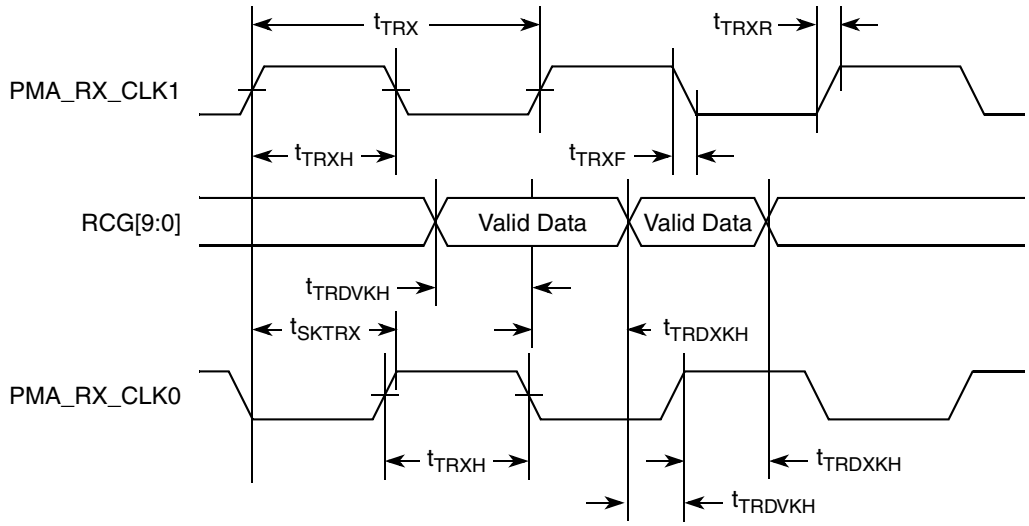


Figure 20. TBI Receive AC Timing Diagram

8.7.3 TBI Single-Clock Mode AC Specifications

When the eTSEC is configured for TBI modes, all clocks are supplied from external sources to the relevant eTSEC interface. In single-clock TBI mode, when TBICON[CLKSEL] = 1, a 125-MHz TBI receive clock is supplied on the TSEC*n*_RX_CLK pin (no receive clock is used on TSEC*n*_TX_CLK in this mode, whereas for the dual-clock mode this is the PMA1 receive clock). The 125-MHz transmit clock is applied on the TSEC_GTX_CLK125 pin in all TBI modes.

Figure 37 provides the boundary-scan timing diagram.

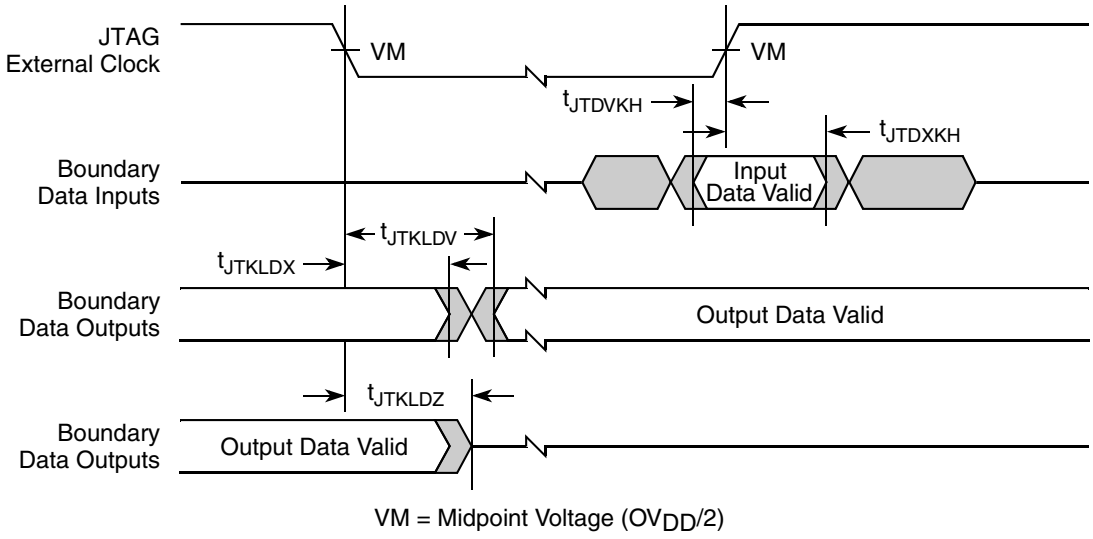


Figure 37. Boundary-Scan Timing Diagram

13 I²C

This section describes the DC and AC electrical characteristics for the I²C interfaces of the MPC8544E.

13.1 I²C DC Electrical Characteristics

Table 51 provides the DC electrical characteristics for the I²C interfaces.

Table 51. I²C DC Electrical Characteristics

At recommended operating conditions with OV_{DD} of 3.3 V ± 5%.

Parameter	Symbol	Min	Max	Unit	Notes
Input high voltage level	V_{IH}	$0.7 \times OV_{DD}$	$OV_{DD} + 0.3$	V	—
Input low voltage level	V_{IL}	–0.3	$0.3 \times OV_{DD}$	V	—
Low level output voltage	V_{OL}	0	$0.2 \times OV_{DD}$	V	1
Pulse width of spikes which must be suppressed by the input filter	t_{I2KHKL}	0	50	ns	2
Input current each I/O pin (input voltage is between $0.1 \times OV_{DD}$ and $0.9 \times OV_{DD}$(max)	I_I	–10	10	μA	3
Capacitance for each I/O pin	C_I	—	10	pF	—

Notes:
1. Output voltage (open drain or open collector) condition = 3 mA sink current.
2. Refer to the *MPC8544EPowerQUICC III Integrated Communications Host Processor Reference Manual* for information on the digital filter used.
3. I/O pins will obstruct the SDA and SCL lines if OV_{DD} is switched off.

14.2 GPIO AC Electrical Specifications

Table 54 provides the GPIO input and output AC timing specifications.

Table 54. GPIO Input AC Timing Specifications

Parameter	Symbol	Typ	Unit	Notes
GPIO inputs—minimum pulse width	t_{PIWID}	20	ns	1

Note:
1. GPIO inputs and outputs are asynchronous to any visible clock. GPIO outputs should be synchronized before use by any external synchronous logic. GPIO inputs are required to be valid for at least t_{PIWID} ns to ensure proper operation.

Figure 40 provides the AC test load for the GPIO.

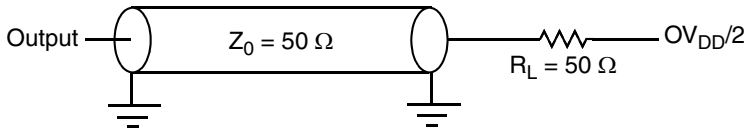


Figure 40. GPIO AC Test Load

15 PCI

This section describes the DC and AC electrical specifications for the PCI bus of the MPC8544E.

15.1 PCI DC Electrical Characteristics

Table 55 provides the DC electrical characteristics for the PCI interface.

Table 55. PCI DC Electrical Characteristics [1]

Parameter	Symbol	Min	Max	Unit	Notes
High-level input voltage	V_{IH}	2	OV_{DD} + 0.3	V	—
Low-level input voltage	V_{IL}	–0.3	0.8	V	—
Input current (V_{IN} = 0 V or V_{IN} = V_{DD})	I_{IN}	—	±5	μA	2
High-level output voltage (OV_{DD} = min, I_{OH} = –2mA)	V_{OH}	2.4	—	V	—
Low-level output voltage (OV_{DD} = min, I_{OL} = 2 mA)	V_{OL}	—	0.4	V	—

Notes:
1. Ranges listed do not meet the full range of the DC specifications of the *PCI 2.2 Local Bus Specifications*.
2. Note that the symbol V_{IN}, in this case, represents the OV_{IN} symbol referenced in Table 1 and Table 2.

Using this waveform, the definitions are as follows. To simplify illustration, the following definitions assume that the SerDes transmitter and receiver operate in a fully symmetrical differential signaling environment.

1. **Single-Ended Swing**

   The transmitter output signals and the receiver input signals SD*n*_TX, $\overline{\text{SD}n\text{\_TX}}$, SD*n*_RX and $\overline{\text{SD}n\text{\_RX}}$ each have a peak-to-peak swing of A - B Volts. This is also referred as each signal wire's Single-Ended Swing.

2. **Differential Output Voltage, V_{OD}** (or **Differential Output Swing**):

   The Differential Output Voltage (or Swing) of the transmitter, V_{OD}, is defined as the difference of the two complimentary output voltages: $V_{SDn\_TX} - V_{\overline{SDn\_TX}}$. The V_{OD} value can be either positive or negative.

3. **Differential Input Voltage, V_{ID}** (or **Differential Input Swing**):

   The Differential Input Voltage (or Swing) of the receiver, V_{ID}, is defined as the difference of the two complimentary input voltages: $V_{SDn\_RX} - V_{\overline{SDn\_RX}}$. The V_{ID} value can be either positive or negative.

4. **Differential Peak Voltage, V_{DIFFp}**

   The peak value of the differential transmitter output signal or the differential receiver input signal is defined as Differential Peak Voltage, $V_{DIFFp} = |A - B|$ Volts.

5. **Differential Peak-to-Peak, $V_{DIFFp-p}$**

   Since the differential output signal of the transmitter and the differential input signal of the receiver each range from A – B to –(A – B) Volts, the peak-to-peak value of the differential transmitter output signal or the differential receiver input signal is defined as Differential Peak-to-Peak Voltage, $V_{DIFFp-p} = 2*V_{DIFFp} = 2 * |(A - B)|$ Volts, which is twice of differential swing in amplitude, or twice of the differential peak. For example, the output differential peak-peak voltage can also be calculated as $V_{TX-DIFFp-p} = 2*|V_{OD}|$.

6. **Differential Waveform**

   The differential waveform is constructed by subtracting the inverting signal ($\overline{\text{SD}n\text{\_TX}}$, for example) from the non-inverting signal (SD*n*_TX, for example) within a differential pair. There is only one signal trace curve in a differential waveform. The voltage represented in the differential waveform is not referenced to ground. Refer to Figure 44 as an example for differential waveform.

7. **Common Mode Voltage, V_{cm}**

   The Common Mode Voltage is equal to one half of the sum of the voltages between each conductor of a balanced interchange circuit and ground. In this example, for SerDes output, $V_{cm\_out} = V_{SDn\_TX} + V_{\overline{SDn\_TX}} = (A + B) / 2$, which is the arithmetic mean of the two complimentary output voltages within a differential pair. In a system, the common mode voltage may often differ from one component's output to the other's input. Sometimes, it may be even different between the receiver input and driver output circuits within the same component. It is also referred as the DC offset in some occasions.

— For **external DC-coupled** connection, as described in Section 16.2.1, "SerDes Reference Clock Receiver Characteristics," the maximum average current requirements sets the requirement for average voltage (common mode voltage) to be between 100 and 400 mV. Figure 46 shows the SerDes reference clock input requirement for DC-coupled connection scheme.

— For **external AC-coupled** connection, there is no common mode voltage requirement for the clock driver. Since the external AC-coupling capacitor blocks the DC level, the clock driver and the SerDes reference clock receiver operate in different command mode voltages. The SerDes reference clock receiver in this connection scheme has its common mode voltage set to SGND_SRDS*n*. Each signal wire of the differential inputs is allowed to swing below and above the command mode voltage (SGND_SRDS*n*). Figure 47 shows the SerDes reference clock input requirement for AC-coupled connection scheme.

- **Single-ended Mode**
  — The reference clock can also be single-ended. The SD*n*_REF_CLK input amplitude (single-ended swing) must be between 400 and 800 mV peak-peak (from Vmin to Vmax) with $\overline{\text{SD}n\text{\_REF\_CLK}}$ either left unconnected or tied to ground.
  — The SD*n*_REF_CLK input average voltage must be between 200 and 400 mV. Figure 48 shows the SerDes reference clock input requirement for single-ended signaling mode.
  — To meet the input amplitude requirement, the reference clock inputs might need to be DC or AC-coupled externally. For the best noise performance, the reference of the clock could be DC or AC-coupled into the unused phase ($\overline{\text{SD}n\text{\_REF\_CLK}}$) through the same source impedance as the clock input (SD*n*_REF_CLK) in use.

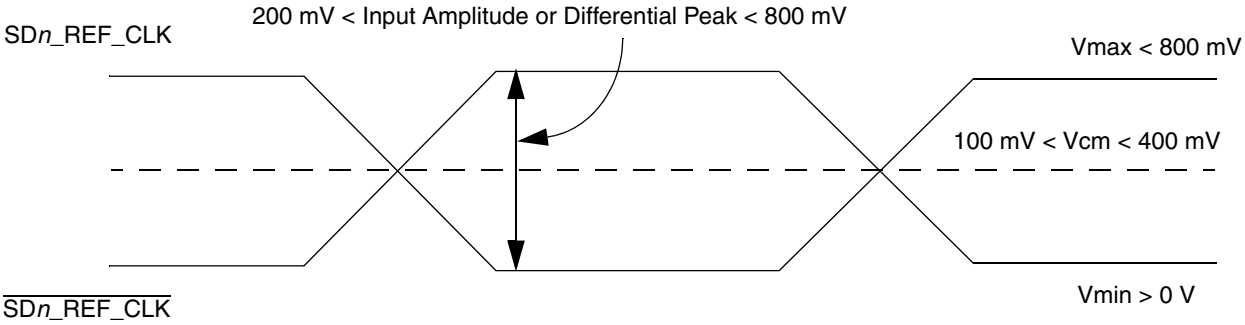


Figure 46. Differential Reference Clock Input DC Requirements (External DC-Coupled)

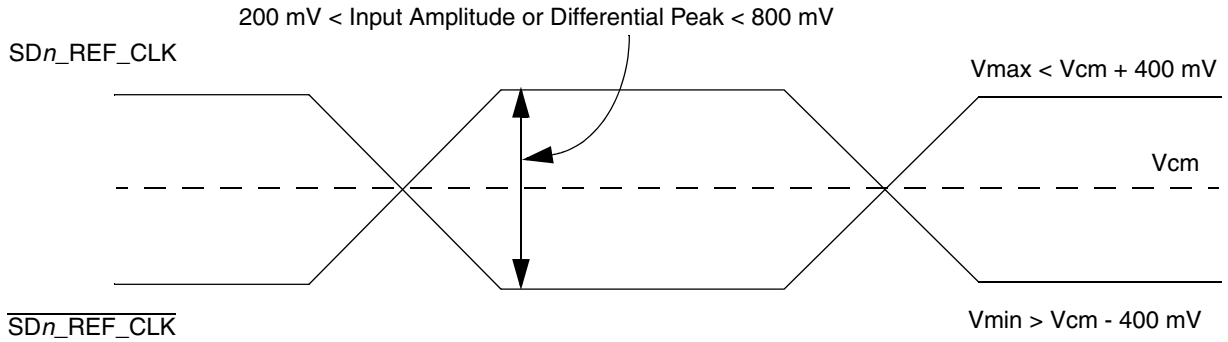


Figure 47. Differential Reference Clock Input DC Requirements (External AC-Coupled)

16.2.4 AC Requirements for SerDes Reference Clocks

The clock driver selected should provide a high quality reference clock with low phase noise and cycle-to-cycle jitter. Phase noise less than 100 kHz can be tracked by the PLL and data recovery loops and is less of a problem. Phase noise above 15 MHz is filtered by the PLL. The most problematic phase noise occurs in the 1–15 MHz range. The source impedance of the clock driver should be 50 Ω to match the transmission line and reduce reflections which are a source of noise to the system.

Table 57 describes some AC parameters common to SGMII, and PCI Express protocols.

Table 57. SerDes Reference Clock Common AC Parameters

Parameter	Symbol	Min	Max	Unit	Notes
Rising Edge Rate	Rise Edge Rate	1.0	4.0	V/ns	2, 3
Falling Edge Rate	Fall Edge Rate	1.0	4.0	V/ns	2, 3
Differential Input High Voltage	V_{IH}	+200	—	mV	2
Differential Input Low Voltage	V_{IL}	—	–200	mV	2
Rising edge rate (SD*n*_REF_CLK) to falling edge rate ($\overline{\text{SD}n\text{\_REF\_CLK}}$) matching	Rise-Fall Matching	—	20	%	1, 4

Notes:
1. Measurement taken from single ended waveform.
2. Measurement taken from differential waveform.
3. Measured from –200 mV to +200 mV on the differential waveform (derived from SD*n*_REF_CLK minus $\overline{\text{SD}n\text{\_REF\_CLK}}$). The signal must be monotonic through the measurement region for rise and fall time. The 400 mV measurement window is centered on the differential zero crossing. See Figure 53.
4. Matching applies to rising edge rate for SD*n*_REF_CLK and falling edge rate for $\overline{\text{SD}n\text{\_REF\_CLK}}$. It is measured using a 200 mV window centered on the median cross point where SD*n*_REF_CLK rising meets $\overline{\text{SD}n\text{\_REF\_CLK}}$ falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations. The rise edge rate of SD*n*_REF_CLK should be compared to the fall edge rate of $\overline{\text{SD}n\text{\_REF\_CLK}}$, the maximum allowed difference should not exceed 20% of the slowest edge rate. See Figure 54.

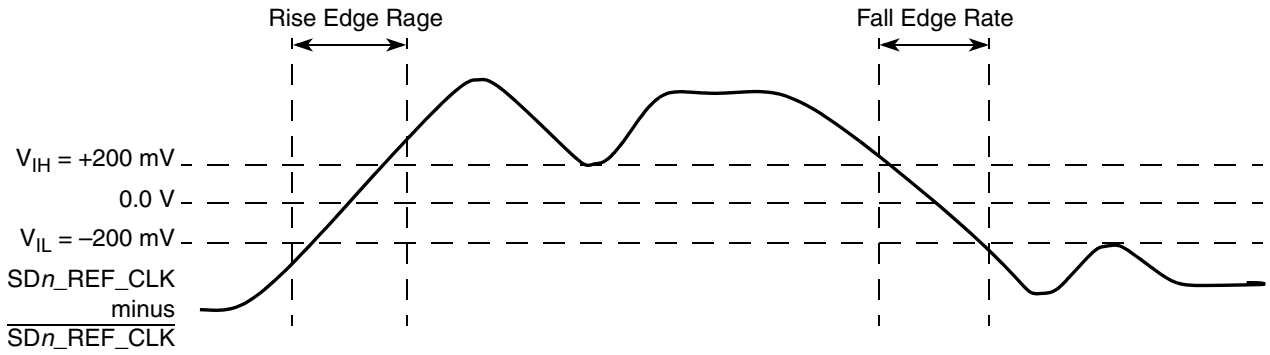


Figure 53. Differential Measurement Points for Rise and Fall Time

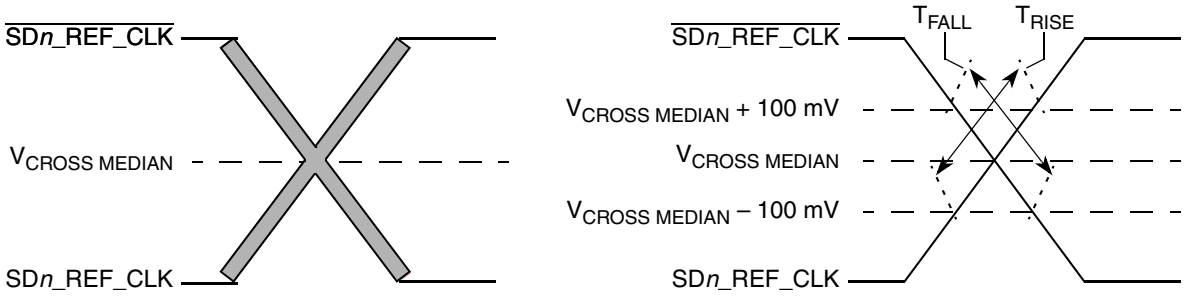


Figure 54. Single-Ended Measurement Points for Rise and Fall Time Matching

The other detailed AC requirements of the SerDes reference clocks is defined by each interface protocol based on application usage. Refer to the following sections for detailed information:

- Section 8.3.1, "The $\overline{\text{DBWO}}$ Signal"
- Section 17.2, "AC Requirements for PCI Express SerDes Clocks"

16.2.4.1 Spread Spectrum Clock

SD1_REF_CLK/$\overline{\text{SD1\_REF\_CLK}}$ were designed to work with a spread spectrum clock (+0 to –0.5% spreading at 30–33 kHz rate is allowed), assuming both ends have same reference clock. For better results, a source without significant unintended modulation should be used.

SD2_REF_CLK/$\overline{\text{SD2\_REF\_CLK}}$ are not intended to be used with, and should not be clocked by, a spread spectrum clock source.

16.3 SerDes Transmitter and Receiver Reference Circuits

Figure 55 shows the reference circuits for SerDes data lane's transmitter and receiver.

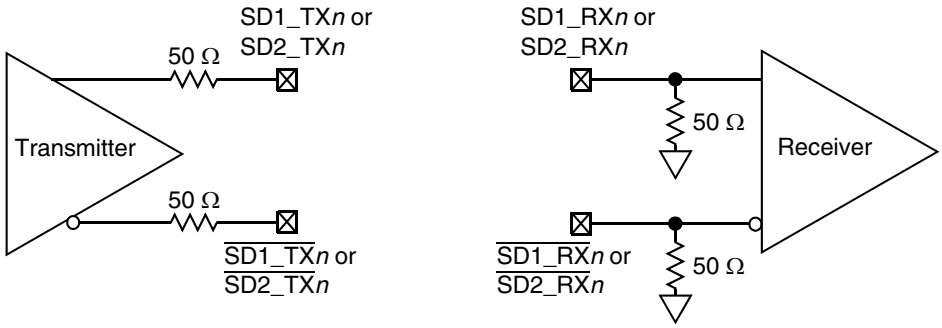


Figure 55. SerDes Transmitter and Receiver Reference Circuits

The DC and AC specification of SerDes data lanes are defined in the section below (PCI Express or SGMII) in this document based on the application usage:

- Section 8.3, "SGMII Interface Electrical Characteristics"
- Section 17, "PCI Express"

Please note that external AC Coupling capacitor is required for the above serial transmission protocols with the capacitor value defined in specification of each protocol section.

17 PCI Express

This section describes the DC and AC electrical specifications for the PCI Express bus of the MPC8544.

17.1 DC Requirements for PCI Express SD_REF_CLK and $\overline{\text{SD\_REF\_CLK}}$

For more information, see Section 16.2, "SerDes Reference Clocks."

17.2 AC Requirements for PCI Express SerDes Clocks

Table 58 provides the AC requirements for the PCI Express SerDes clocks.

Table 58. SD_REF_CLK and $\overline{\text{SD\_REF\_CLK}}$ AC Requirements

Symbol[2]	Parameter Description	Min	Typ	Max	Units	Notes
t_{REF}	REFCLK cycle time	—	10	—	ns	1
t_{REFCJ}	REFCLK cycle-to-cycle jitter. Difference in the period of any two adjacent REFCLK cycles	—	—	100	ps	—
t_{REFPJ}	Phase jitter. Deviation in edge location with respect to mean edge location	–50	—	50	ps	—

Notes:
1. Typical based on *PCI Express Specification 2.0*.
2. Guaranteed by characterization.

17.3 Clocking Dependencies

The ports on the two ends of a link must transmit data at a rate that is within 600 parts per million (ppm) of each other at all times. This is specified to allow bit rate clock sources with a ±300 ppm tolerance.

17.4 Physical Layer Specifications

The following is a summary of the specifications for the physical layer of PCI Express on this device. For further details as well as the specifications of the transport and data link layer please refer to the *PCI Express Base Specification*. *Rev. 1.0a*.

Table 62. MPC8544E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
LCS6/DMA_DACK2	J16	O	BV_{DD}	1
LCS7/DMA_DDONE2	L18	O	BV_{DD}	1
LWE0/LBS0/LSDDQM[0]	J22	O	BV_{DD}	4, 8
LWE1/LBS1/LSDDQM[1]	H22	O	BV_{DD}	4, 8
LWE2/LBS2/LSDDQM[2]	H23	O	BV_{DD}	4, 8
LWE3/LBS3/LSDDQM[3]	H21	O	BV_{DD}	4, 8
LALE	J26	O	BV_{DD}	4, 7, 8
LBCTL	J25	O	BV_{DD}	4, 7, 8
LGPL0/LSDA10	J20	O	BV_{DD}	4, 8
LGPL1/LSDWE	K20	O	BV_{DD}	4, 8
LGPL2/LOE/LSDRAS	G20	O	BV_{DD}	4, 7, 8
LGPL3/LSDCAS	H18	O	BV_{DD}	4, 8
LGPL4/LGTA/LUPWAIT/ LPBSE	L20	I/O	BV_{DD}	28
LGPL5	K19	O	BV_{DD}	4, 8
LCKE	L17	O	BV_{DD}	—
LCLK[0:2]	H24, J24, H25	O	BV_{DD}	—
LSYNC_IN	D27	I	BV_{DD}	—
LSYNC_OUT	D28	O	BV_{DD}	—
DMA				
DMA_DACK[0:1]	Y13, Y12	O	OV_{DD}	4, 8, 9
DMA_DREQ[0:1]	AA10, AA11	I	OV_{DD}	—
DMA_DDONE[0:1]	AA7, Y11	O	OV_{DD}	—
Programmable Interrupt Controller				
UDE	AH15	I	OV_{DD}	—
MCP	AG18	I	OV_{DD}	—
IRQ[0:7]	AG22, AF17, AD21, AF19, AG17, AF16, AC23, AC22	I	OV_{DD}	—
IRQ[8]	AC19	I	OV_{DD}	—
IRQ[9]/DMA_DREQ3	AG20	I	OV_{DD}	1
IRQ[10]/DMA_DACK3	AE27	I/O	OV_{DD}	1
IRQ[11]/DMA_DDONE3	AE24	I/O	OV_{DD}	1
IRQ_OUT	AD14	O	OV_{DD}	2

Table 62. MPC8544E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
$\overline{\text{SD2\_REF\_CLK}}$	AF2	I	XV_{DD}	—
SD2_TST_CLK	AG4	—	—	—
$\overline{\text{SD2\_TST\_CLK}}$	AF4	—	—	—
General-Purpose Output				
GPOUT[0:7]	AF22, AH23, AG27, AH25, AF21, AF25, AG26, AF26	O	OV_{DD}	—
General-Purpose Input				
GPIN[0:7]	AH24, AG24, AD23, AE21, AD22, AF23, AG25, AE20	I	OV_{DD}	—
System Control				
$\overline{\text{HRESET}}$	AG16	I	OV_{DD}	—
$\overline{\text{HRESET\_REQ}}$	AG15	O	OV_{DD}	21
$\overline{\text{SRESET}}$	AG19	I	OV_{DD}	—
$\overline{\text{CKSTP\_IN}}$	AH5	I	OV_{DD}	—
$\overline{\text{CKSTP\_OUT}}$	AA12	O	OV_{DD}	2, 4
Debug				
TRIG_IN	AC5	I	OV_{DD}	—
TRIG_OUT/READY/ $\overline{\text{QUIESCE}}$	AB5	O	OV_{DD}	5, 8, 15, 21
MSRCID[0:1]	Y7, W9	O	OV_{DD}	4, 5, 8
MSRCID[2:4]	AA9, AB6, AD5	O	OV_{DD}	5, 15, 21
MDVAL	Y8	O	OV_{DD}	5
CLK_OUT	AE16	O	OV_{DD}	10
Clock				
RTC	AF15	I	OV_{DD}	—
SYSCLK	AH16	I	OV_{DD}	—
JTAG				
TCK	AG28	I	OV_{DD}	—
TDI	AH28	I	OV_{DD}	11
TDO	AF28	O	OV_{DD}	10
TMS	AH27	I	OV_{DD}	11
$\overline{\text{TRST}}$	AH22	I	OV_{DD}	11

Note that there is no default for this PLL ratio; these signals must be pulled to the desired values. Also note that the DDR data rate is the determining factor in selecting the CCB bus frequency, since the CCB frequency must equal the DDR data rate.

Table 65. CCB Clock Ratio

Binary Value of LA[28:31] Signals	CCB:SYSCLK Ratio	Binary Value of LA[28:31] Signals	CCB:SYSCLK Ratio
0000	16:1	1000	8:1
0001	Reserved	1001	9:1
0010	Reserved	1010	10:1
0011	3:1	1011	Reserved
0100	4:1	1100	12:1
0101	5:1	1101	Reserved
0110	6:1	1110	Reserved
0111	Reserved	1111	Reserved

19.3 e500 Core PLL Ratio

Table 66 describes the clock ratio between the e500 core complex bus (CCB) and the e500 core clock. This ratio is determined by the binary value of LBCTL, LALE, and LGPL2 at power up, as shown in Table 66.

Table 66. e500 Core to CCB Clock Ratio

Binary Value of LBCTL, LALE, LGPL2 Signals	e500 core:CCB Clock Ratio	Binary Value of LBCTL, LALE, LGPL2 Signals	e500 core:CCB Clock Ratio
000	4:1	100	2:1
001	Reserved	101	5:2
010	Reserved	110	3:1
011	3:2	111	7:2

19.4 PCI Clocks

For specifications on the PCI_CLK, refer to the *PCI 2.2 Local Bus Specifications*.

The use of PCI_CLK is optional if SYSCLK is in the range of 33–66 MHz. If SYSCLK is outside this range then use of PCI_CLK is required as a separate PCI clock source, asynchronous with respect to SYSCLK.

19.5 Security Controller PLL Ratio

Table 67 shows the SEC frequency ratio.

Table 67. SEC Frequency Ratio

Signal Name	Value (Binary)	CCB CLK:SEC CLK
LWE_B	0	2:1[1]
	1	3:1[2]

Notes:
1. In 2:1 mode the CCB frequency must be operating ≤ 400 MHz.
2. In 3:1 mode any valid CCB can be used. The 3:1 mode is the default ratio for security block.

19.6 Frequency Options

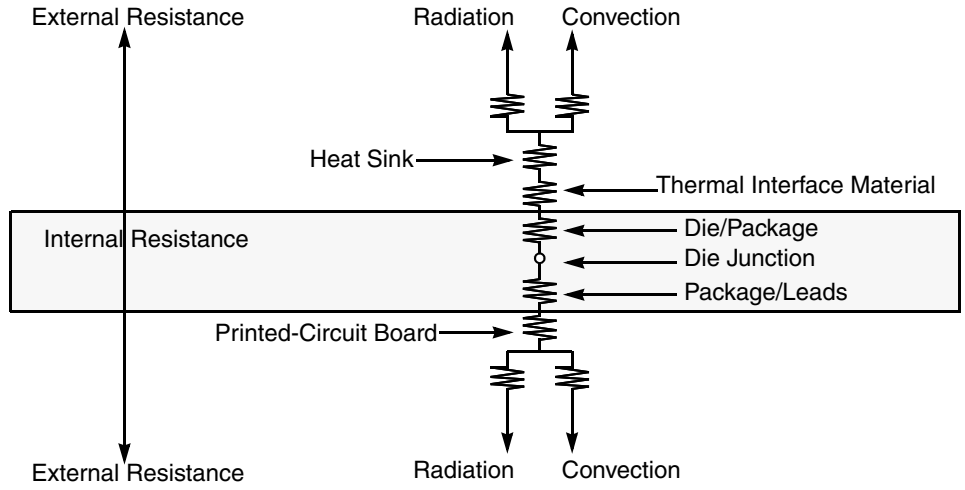
19.6.1 SYSCLK to Platform Frequency Options

Table 68 shows the expected frequency values for the platform frequency when using a CCB clock to SYSCLK ratio in comparison to the memory bus clock speed.

Table 68. Frequency Options of SYSCLK with Respect to Memory Bus Speeds

CCB to SYSCLK Ratio	SYSCLK (MHz)						
	33.33	41.66	66.66	83	100	111	133.33
	Platform /CCB Frequency (MHz)						
2							—
3					—	333	400
4			—	333	400	445	533
5			333	415	500		
6			400	500			
8		333	533				
9		375					
10	333	417					
12	400	500					
16	533						

Figure 62 depicts the primary heat transfer path for a package with an attached heat sink mounted to a printed-circuit board.



(Note the internal versus external package resistance.)

Figure 62. Package with Heat Sink Mounted to a Printed-Circuit Board

The heat sink removes most of the heat from the device. Heat generated on the active side of the chip is conducted through the silicon and through the heat sink attach material (or thermal interface material), and finally to the heat sink. The junction-to-case thermal resistance is low enough that the heat sink attach material and heat sink thermal resistance are the dominant terms.

20.3.2 Thermal Interface Materials

A thermal interface material is required at the package-to-heat sink interface to minimize the thermal contact resistance. For those applications where the heat sink is attached by spring clip mechanism, Figure 63 shows the thermal performance of three thin-sheet thermal-interface materials (silicone, graphite/oil, floroether oil), a bare joint, and a joint with thermal grease as a function of contact pressure. As shown, the performance of these thermal interface materials improves with increasing contact pressure. The use of thermal grease significantly reduces the interface thermal resistance. The bare joint results in a thermal resistance approximately six times greater than the thermal grease joint.

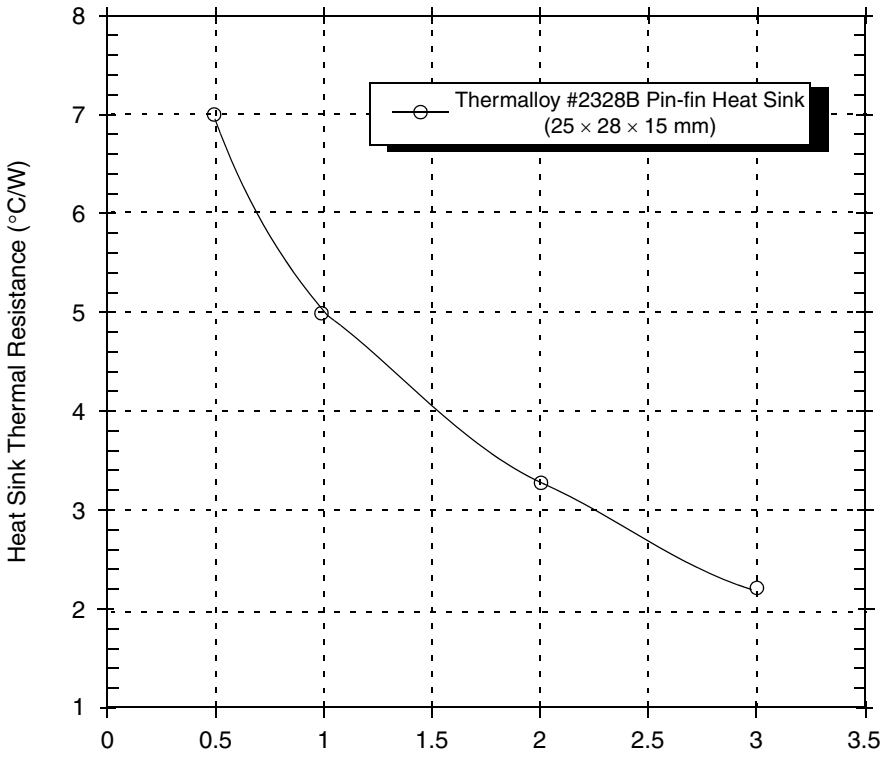


Figure 64. Approach Air Velocity (m/s)

20.3.4 Temperature Diode

The MPC8544E has a temperature diode on the microprocessor that can be used in conjunction with other system temperature monitoring devices (such as Analog Devices, ADT7461™). These devices use the negative temperature coefficient of a diode operated at a constant current to determine the temperature of the microprocessor and its environment. It is recommended that each device be individually calibrated.

The following are voltage forward biased range of the on-board temperature diode:

$V_f > 0.40$ V

$V_f < 0.90$ V

An approximate value of the ideality may be obtained by calibrating the device near the expected operating temperature. The ideality factor is defined as the deviation from the ideal diode equation:

$$I_{fw} = \mathbf{I_s}\left[e^{\frac{qV_f}{nKT}} - \mathbf{1}\right]$$

Another useful equation is:

$$\mathbf{V_H - V_L = n}\frac{KT}{q}\left[\boldsymbol{ln}\ \frac{I_H}{I_L}\right]$$

21.5 Connection Recommendations

To ensure reliable operation, it is highly recommended to connect unused inputs to an appropriate signal level. All unused active low inputs should be tied to V_{DD}, TV_{DD}, BV_{DD}, OV_{DD}, GV_{DD}, and LV_{DD} as required. All unused active high inputs should be connected to GND. All NC (no connect) signals must remain unconnected. Power and ground connections must be made to all external V_{DD}, TV_{DD}, BV_{DD}, OV_{DD}, GV_{DD}, and LV_{DD}, and GND pins of the device.

21.6 Pull-Up and Pull-Down Resistor Requirements

The MPC8544E requires weak pull-up resistors (2–10 kΩ is recommended) on open drain type pins including I^2C pins and MPIC interrupt pins.

Correct operation of the JTAG interface requires configuration of a group of system control pins as demonstrated in Figure 69. Care must be taken to ensure that these pins are maintained at a valid deasserted state under normal operating conditions as most have asynchronous behavior and spurious assertion will give unpredictable results.

The following pins must NOT be pulled down during power-on reset: TSEC3_TXD[3], $\overline{\text{HRESET\_REQ}}$, TRIG_OUT/READY/$\overline{\text{QUIESCE}}$, MSRCID[2:4], ASLEEP. The $\overline{\text{DMA\_DACK}}$[0:1] and $\overline{\text{TEST\_SEL}}$ pins must be set to a proper state during POR configuration. Refer to the pinout listing table (Table 62) for more details. Refer to the *PCI 2.2 Local Bus Specifications,* for all pullups required for PCI.

21.7 Output Buffer DC Impedance

The MPC8544E drivers are characterized over process, voltage, and temperature. For all buses, the driver is a push-pull single-ended driver type (open drain for I^2C). To measure Z_0 for the single-ended drivers, an external resistor is connected from the chip pad to OV_{DD} or GND. Then, the value of each resistor is varied until the pad voltage is $OV_{DD}/2$ (see Figure 67). The output impedance is the average of two components, the resistances of the pull-up and pull-down devices. When data is held high, SW1 is closed (SW2 is open) and R_P is trimmed until the voltage at the pad equals $OV_{DD}/2$. R_P then becomes the

21.10 Guidelines for High-Speed Interface Termination

This section provides guidelines for when the SerDes interface is either not used at all or only partly used.

21.10.1 SerDes Interface Entirely Unused

If the high-speed SerDes interface is not used at all, the unused pin should be terminated as described in this section. However, the SerDes must always have power applied to its supply pins.

The following pins must be left unconnected (float):

- SD_TX[0:7]
- $\overline{\text{SD\_TX}}$[0:7]

The following pins must be connected to GND:

- SD_RX[0:7]
- $\overline{\text{SD\_RX}}$[0:7]
- SD_REF_CLK
- $\overline{\text{SD\_REF\_CLK}}$

21.10.2 SerDes Interface Partly Unused

If only part of the high speed SerDes interface pins are used, the remaining high-speed serial I/O pins should be terminated as described in this section.

The following pins must be left unconnected (float) if not used:

- SD_TX[0:7]
- $\overline{\text{SD\_TX}}$[0:7]

The following pins must be connected to GND if not used:

- SD_RX[0:7]
- $\overline{\text{SD\_RX}}$[0:7]
- SD_REF_CLK
- $\overline{\text{SD\_REF\_CLK}}$

21.11 Guideline for PCI Interface Termination

PCI termination, if not used at all, is done as follows.

Option 1

- If PCI arbiter is enabled during POR,
- All AD pins will be driven to the stable states after POR. Therefore, all ADs pins can be floating.
- All PCI control pins can be grouped together and tied to OV_{DD} through a single 10-kΩ resistor.
- It is optional to disable PCI block through DEVDISR register after POR reset.